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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

I Applicant: Steinmann et al

Art Unit: 1765

Serial No.: 09/852,921

Examiner: Deo, D.

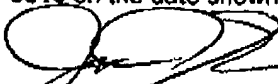
Filing Date: 05/10/01

Docket No.: TI-29881

Title: METHOD OF INTEGRATING A THIN FILM RESISTOR IN A
MULTI-LEVEL METAL TUNGSTEN-PLUG INTERCONNECT

CERTIFICATION OF FACSIMILE TRANSMISSION

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FACSIMILE COVER SHEET

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NAME OF INVENTOR(S): Steinmann		RECEIPT DATE & SERIAL NO.: Serial No.: 09/852,921	
TITLE OF INVENTION: Method of Integrating a Thin Film Resistor		Filing Date: 05/10/2110	
TI FILE NO.: TI-29881	DEPOSIT ACCT. NO.: 20-0668		
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